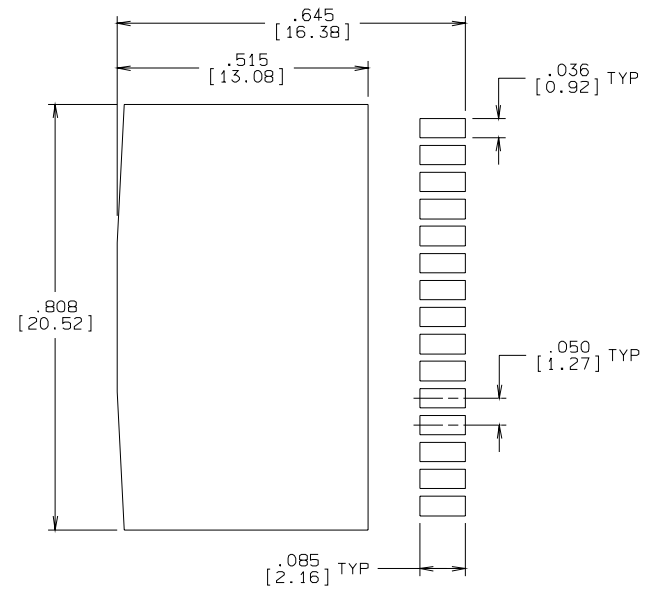
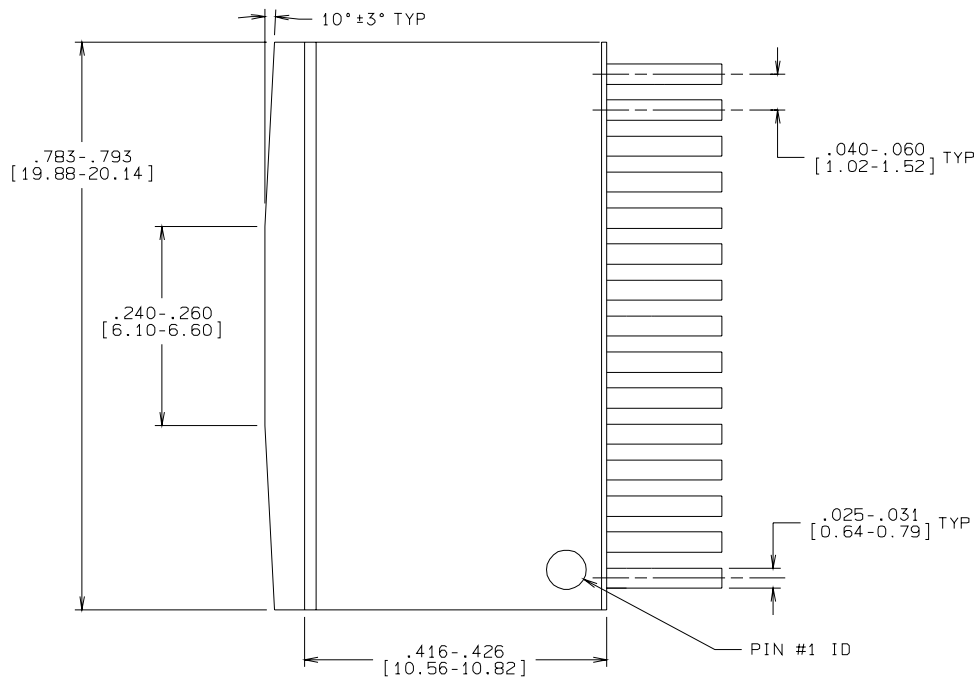
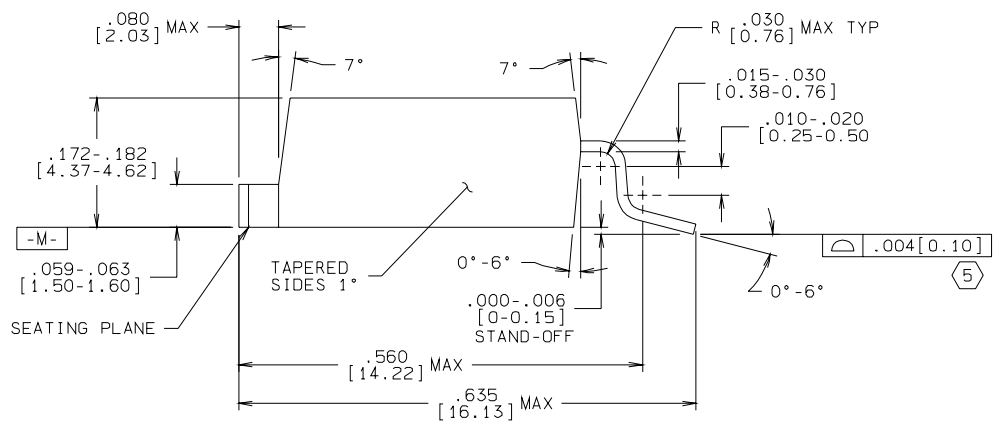


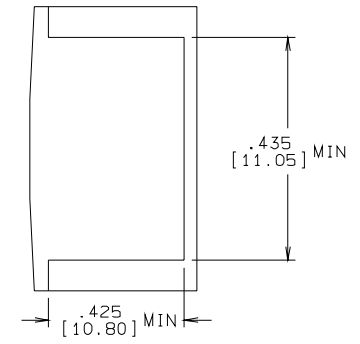
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09829	06/21/93	DEG/FL
B	REV LEADS: ADD .000-.006 STAND-OFF & NOTE 5	10152	12/02/93	TL/



LEAD POSITION OVERLAY



CONTROLLING DIMENSION: INCH



BACK VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH: 200 MICROINCHES / 5.08 MICROMETERS MINIMUM LEAD/TIN 15/85 ON OLIN 194 COPPER OR EQUIVALENT.
 - MAXIMUM VERTICAL BURR ON HEATSINK NOT TO EXCEED .003 IN/ 0.05 mm.
 - NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION ALLOWED AFTER FORMING.
 - JEDEC IS IN PROGRESS FOR BALLOT #10-340 AS OF 6/16/93.
- 5 UNDER ALL CONDITIONS, LEAD(S) MUST NOT BE ABOVE DATUM -M- AND NO LEADS MAY BE LOWER THAN .006 IN/ 0.15 mm MEASURED FROM DATUM -M- TO THE BOTTOM OF THE LEADS.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN D.E. GRADY	06/21/93	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		TO-263, MOLDED, 15 LEAD, SURFACE MOUNT		
ENGR. CHK.				
APPROVAL				
PROJECTION 	SCALE N/A	SIZE C	DRAWING NUMBER MKT-TS15B	REV B
DO NOT SCALE DRAWING		SHEET 1 OF 1		